			In
	Application No.	Applicant(s)	
Notice of Allowability	09/516,080	BOLKEN, TODD O.	
	Examin r	Art Unit	
	Wai-Sing Louie	2814	
The MAILING DATE of this communication appeared all claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT R of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this or other appropriate communications. This application is subjection.	s application. If not included ation will be mailed in due course.	
1. This communication is responsive to 7/28.			
2. X The allowed claim(s) is/are <u>1-14 and 16-20</u> .			
3. \boxtimes The drawings filed on <u>01 March 2000</u> are accepted by the	Examiner.	•	
 Acknowledgment is made of a claim for foreign priority una) ☐ All b) ☐ Some* c) ☐ None of the: 	nder 35 U.S.C. § 119(a)-(d) or (f).	
 Certified copies of the priority documents have 	e been received.		
Certified copies of the priority documents have	e been received in Application N	0	
Copies of the certified copies of the priority do	cuments have been received in	this national stage application fro	m the
International Bureau (PCT Rule 17.2(a)).			
* Certified copies not received:		·	
5. Acknowledgment is made of a claim for domestic priority u reference was included in the first sentence of the specific	ation or in an Application Data S		cific
(a) The translation of the foreign language provisional a			
6. Acknowledgment is made of a claim for domestic priority u in the first sentence of the specification or in an Application		21 since a specific reference was	included
Applicant has THREE MONTHS FROM THE "MAILING DATE" o below. Failure to timely comply will result in ABANDONMENT of	f this communication to file a rep this application. THIS THREE-	ly complying with the requiremen MONTH PERIOD IS NOT EXTEN	ts noted NDABLE.
7. A SUBSTITUTE OATH OR DECLARATION must be subm INFORMAL PATENT APPLICATION (PTO-152) which giv			OF
8. CORRECTED DRAWINGS (as "replacement sheets") must (a) including changes required by the Notice of Draftspers 1) hereto or 2) to Paper No		PTO-948) attached	
(b) including changes required by the proposed drawing correction filed, which has been approved by the Examiner.			
(c) ☐ including changes required by the attached Examiner	s Amendment / Comment or in t	he Office action of Paper No	·
Identifying indicia such as the application number (see 37 CFR 1 each sheet. Replacement sheet(s) should be labeled as such in t	.84(c)) should be written on the di the margin according to 37 CFR 1.	rawings in the front (not the back) of 121(d).	of
9. DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT FOR 1	sit of BIOLOGICAL MATERIA THE DEPOSIT OF BIOLOGICAL	AL must be submitted. Note the MATERIAL.	Э
Attachm nt(s)			
1☐ Notice of References Cited (PTO-892)	5☐ Notice of Informa	al Patent Application (PTO-152)	
2 Notice of Draftperson's Patent Drawing Review (PTO-948)		ary (PTO-413), Paper No	
3 Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No	B), 7☐ Examiner's Ame	ndment/Comment	
4 Examiner's Comment Regarding Requirement for Deposit of Biological Material	8∭ Examiner's State 9∭ Other	ement of Reasons for Allowance	

Application/Control Number: 09/516,080

Art Unit: 2814

DETAILED ACTION

Allowable Subject Matter

Claims 1-14 and 16-20 are allowed. The following is an examiner's statement of reasons for allowance:

The claimed invention is a system for molding a circuit package comprising:

- A first support plate,
- A second support plate proximately positioned with respect to first support plate; and
- A cavity plate positioned between the first support plate and the second support plate, the cavity plate having an aperture configured to accept only a protruding portion of the circuit package such that the protruding portion of the circuit package contacts the first support plate, and where the aperture is sized to create a peripheral void about only the protruding portion of the circuit package to permit a molding compound to be disposed thereabout.

Reference Neu (US 5,405,255) discloses an encapsulation molding apparatus for encapsulating the entire IC chip; therefore, the circuit package does not contact the first support plate.

Reference Chia et al. (US 6,081,997) disclose a packaging system for encapsulating the IC chip. However, Chia et al. do not disclose a cavity plate.

Therefore, the above references do not disclose the claimed invention of the present application and claims 1-14 and 16-20 are allowed.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Wai-Sing Louie whose telephone number is (571) 272-1709. The examiner can normally be reached on 7:30 AM to 4:00 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (571) 272-1562.

PRIMARY EXAMINER

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December 3, 2003.